

L Number	Hits	Search Text	DB	Time stamp
1	2276	((427/8) or (427/9) or (427/10) or (427/240)).CCLS.	USPAT; US-PPGPUB	2003/03/10 07:56
2	1470	((118/712) or (118/52)).CCLS.	USPAT; US-PPGPUB	2003/03/10 07:56
3	132	(156/74).CCLS.	USPAT; US-PPGPUB	2003/03/10 07:56
4	1261	((156/64) or (156/378)).CCLS.	USPAT; US-PPGPUB	2003/03/10 07:56
5	8	((156/74).CCLS.) and wafer	USPAT; US-PPGPUB	2003/03/10 07:56
6	63	((156/64) or (156/378)).CCLS.) and wafer	USPAT; US-PPGPUB	2003/03/10 07:58
7	28	((156/64) or (156/378)).CCLS.) and wafer) and (rotate or rotated or rotating)	USPAT; US-PPGPUB	2003/03/10 07:58
8	11	((156/64) or (156/378)).CCLS.) and wafer) and (rotate or rotated or rotating)) and (temperature)	USPAT; US-PPGPUB	2003/03/10 08:00
9	4536	(wafer or disk) and (rotate or rotated or rotating or spin or spinning or spun) and temperature	EPO; JPO; DERWENT	2003/03/10 08:14
10	780	((wafer or disk) and (rotate or rotated or rotating or spin or spinning or spun) and temperature) and speed	EPO; JPO; DERWENT	2003/03/10 08:01
11	88	((wafer or disk) and (rotate or rotated or rotating or spin or spinning or spun) and temperature) and speed) and (coat or coating or coated)	EPO; JPO; DERWENT	2003/03/10 08:02
12	12	((wafer or disk) and (rotate or rotated or rotating or spin or spinning or spun) and temperature) and speed) and (coat or coating or coated)) and (temperature near3 (disk or wafer))	EPO; JPO; DERWENT	2003/03/10 08:12
13	2	jp-05002777-\$..did.	EPO; JPO; DERWENT	2003/03/10 08:06
14	104	((wafer or disk) and (rotate or rotated or rotating or spin or spinning or spun) and temperature) and speed) and (temperature near3 (disk or wafer))	EPO; JPO; DERWENT	2003/03/10 08:12
15	0	((wafer or disk) and (rotate or rotated or rotating or spin or spinning or spun) and temperature) and speed) and (temperature near3 (disk or wafer))) and bonding	EPO; JPO; DERWENT	2003/03/10 08:13
16	8	((wafer or disk) and (rotate or rotated or rotating or spin or spinning or spun) and temperature) and speed) and (temperature near3 (disk or wafer))) and (temperature near3 (resist or liquid))	EPO; JPO; DERWENT	2003/03/10 08:14
17	2445	(wafer or disk) same (rotate or rotated or rotating or spin or spinning or spun) same temperature	EPO; JPO; DERWENT	2003/03/10 08:16
18	440	((wafer or disk) same (rotate or rotated or rotating or spin or spinning or spun) same temperature) same (temperature near3 (disk or wafer))	EPO; JPO; DERWENT	2003/03/10 08:15
19	24	((wafer or disk) same (rotate or rotated or rotating or spin or spinning or spun) same temperature) same (temperature near3 (disk or wafer))) same (temperature near3 (coating or liquid or resist))	EPO; JPO; DERWENT	2003/03/10 08:16
20	9686	(wafer or disk) same (rotate or rotated or rotating or spin or spinning or spun) same temperature	USPAT; US-PPGPUB	2003/03/10 08:17
21	1854	((wafer or disk) same (rotate or rotated or rotating or spin or spinning or spun) same temperature) same speed	USPAT; US-PPGPUB	2003/03/10 08:17

22	260	((wafer or disk) same (rotate or rotated or rotating or spin or spinning or spun) same temperature same speed) same (temperature near3 (disk or wafer))	USPAT; US-PGPUB	2003/03/10 08:18
23	19	((((wafer or disk) same (rotate or rotated or rotating or spin or spinning or spun) same temperature same speed) same (temperature near3 (disk or wafer))) same (temperature near3 (coating or resist or liquid)))	USPAT; US-PGPUB	2003/03/10 08:21
24	3310	((427/8) or (427/9) or (427/10) or (427/240)).CCLS.) or (((118/712) or (118/52)).CCLS.)	USPAT; US-PGPUB	2003/03/10 08:21
25	53	((((427/8) or (427/9) or (427/10) or (427/240)).CCLS.) or (((118/712) or (118/52)).CCLS.)) and @pd>20030123	USPAT; US-PGPUB	2003/03/10 08:22
26	15	(((((427/8) or (427/9) or (427/10) or (427/240)).CCLS.) or (((118/712) or (118/52)).CCLS.)) and @pd>20030123) and ((rotate or rotated or rotating) same speed)	USPAT; US-PGPUB	2003/03/10 08:22